

::Wafer Back Grinding::

→ FEATURES

- Safe, Clean and Fast grinding
- Maintenance Free
- Easy Operation
- High Accuracy

→ APPLICATION

- Back grinding of MR Head Wafer
- Sizing of Air Bag Sensor
- Surface Grinding of Video Head Block
- Surface Grinding of Hard Material Specimens
- Surface Grinding of FDD Head Slider
- Sizing of Resonator Filter
- Chamfering of OLPF for Camcorder

HRG-150/150F



→ SPECIFICATION

Model	HRG-150	HRG-150F
Wheel Spindle	1.5kW 3,000rpm	5.5kW 3,000rpm
Work Spindle	0.2kW 400rpm	1.5kW 400rpm
Max Workpiece Size	Φ 150 mm	Φ 200 mm
Travel Length	70 mm	70 mm
Feed Rate	0.01 ~5 mm/min	0.01 ~5 mm/min
Resolution	0.001 mm	0.001 mm
Accuracy	± 2μm	± 2μm
Repeatability	± 1μm	± 1μm
Dimension (WxDxH)	1,070 x 500 x 1,460 (mm)	1,070 x 500 x 1,460 (mm)
Weight	700 kg	1,200 kg



→ SPECIFICATION

Model	VRG-250
Wheel Spindle	3.75kW 3,000rpm
Work Spindle	0.37kW 200rpm
Max Workpiece Size	Φ 250
Travel Length	100 mm
Feed Rate	0.01 ~ 10 mm/min
Resolution	0.001 mm
Accuracy	± 2μm
Repeatability	± 1μm
Dimension (WxDxH)	1,100 x 950 x 1,970 mm
Weight	1,450 kg

VRG-400/500



→ SPECIFICATION

Model	VRG-400/500
Wheel Spindle	7.5kW 3,000rpm
Work Spindle	1.5kW 200rpm
Max Workpiece Size	Φ 500
Travel Length	200 mm
Feed Rate	0.01 ~ 10 mm/min
Resolution	0.001 mm
Accuracy	± 2μm
Repeatability	± 1μm
Dimension (WxDxH)	1,300 x 1,400 x 2,100 (mm)
Weight	2,000 kg